

| | |
|-------------------------|---|
| 1. Record Nr. | UNISA990000395250203316 |
| Titolo | Bande armate, banditi, banditismo e repressione di giustizia negli stati europei di antico regime : atti del convegno, Venezia 3-5 novembre 1985 / a cura di Gherardo Ortalli |
| Pubbl/distr/stampa | Roma : Jouvence, 1986 |
| Descrizione fisica | 566 p. ; 21 cm |
| Collana | Storia ; 20 |
| Disciplina | 364.1552094 |
| Soggetti | Brigantaggio - Europa - Sec. 16.-18. - Congressi - 1985 Congressi - Venezia - 1985 |
| Collocazione | 364.155 Ban 1 (ISE V 248) |
| Lingua di pubblicazione | Italiano |
| Formato | Materiale a stampa |
| Livello bibliografico | Monografia |

2. Record Nr.

Titolo

UNINA9910787022703321

11th international congress molded interconnect devices : scientific proceedings : selected, peer reviewed papers from the 11th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany // edited by Jorg Franke [and three others]

Pubbl/distr/stampa

Pfaffikon, Switzerland : , : TTP, , 2014

Enfield, New Hampshire : , : Trans Tech Publications Ltd, , [date of distribution not identified]

©2014

ISBN

3-03826-636-1

Descrizione fisica

1 online resource (119 p.)

Collana

Advanced Materials Research, , 1662-8985 ; ; Volume 1038

Disciplina

621.367

Soggetti

Molded interconnect devices

Three-dimensional display systems

Lingua di pubblicazione

Inglese

Formato

Materiale a stampa

Livello bibliografico

Monografia

Note generali

Description based upon print version of record.

Nota di bibliografia

Includes bibliographical references at the end of each chapters and index.

Nota di contenuto

11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1: Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts Chapter 2: Printing TechnologiesPrinting of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and Manufacturing; Characterization of Electromagnetic Properties of MID

Materials for High Frequency Applications up to 67 GHz
Novel Laser Induced Metallization for Three Dimensional Molded Interconnect Device Applications by Spray Method
Experimental Investigation of Laser Sintering of Conductive Adhesive for Functional Prototypes Produced by Embedding Stereolithography; MID Fabricated by Ultrasonic Processing; Usage of Industrial Robots as Flexible Handling Devices Supporting the Process of Three Dimensional Conductive Pattern Generation; Chapter 4: Manufacturing Processes; Study of MID Technologies for Automotive Lighting and Light Signaling Devices; Chapter 5: Assembly Technologies and Inspection Design and Solder Process Optimization in MID Technology for High Power Applications
Chapter 6: Quality and Reliability; Hot Pin Pull Method - New Test Procedure for the Adhesion Measurement for 3D-MID; Keywords Index; Authors Index

Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers are grouped as follows: Chapter 1: Development and Prototyping, Chapter 2: Printing Technologies, Chapter 3: Materials and Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5: Assembly Technologies and Inspection, Chapter 6: Quality and Reliability.
